

GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2015/09/07	Phebe Su

NOTES:

1.MATERIAL:

- 1.1 HOUSING: HIGH TEMPERATURE THERAL PLASTIC, LCP BLUE
- 1.2 SPRING CONTACT: COPPER ALLOY.
- 1.3 FLAT CONTACT;COPPER ALLOY
- 1.4 SHELL :STAINLESS STEEL.

2.FINISH:

- 2.1 CONTACT: G/F PLATING ON CONTACT AREA,MATTE TIN
PLATING ON SOLDER TAIL AREA,NICKEL UNDER PLATING.
- 2.2 SHELL: SOLDERABILITY NICKEL PLATING OVER ALL.

3.OPERATION TEMPERATURE : -40°C~+85°C

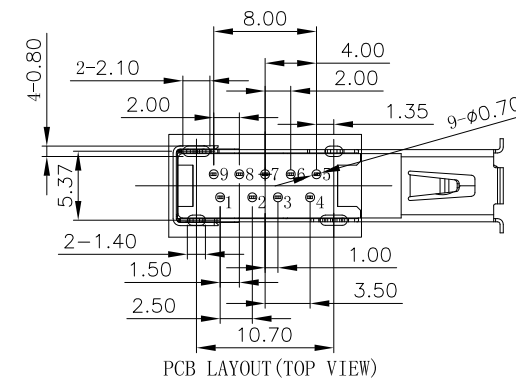
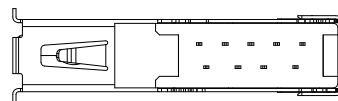
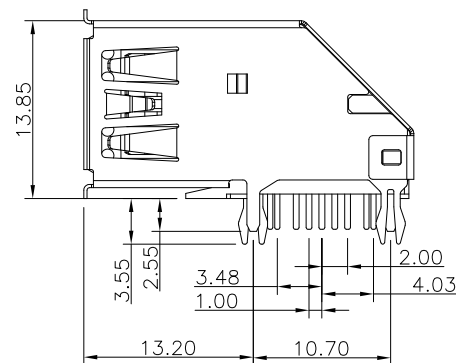
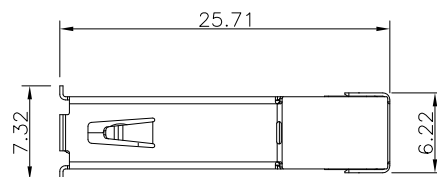
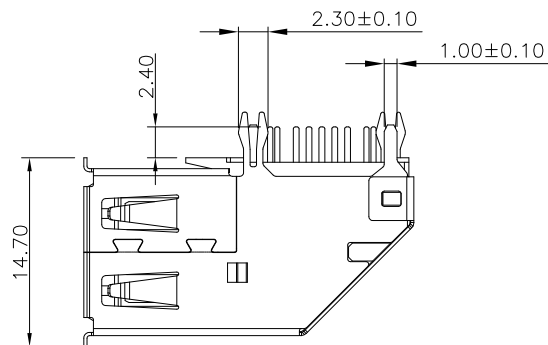
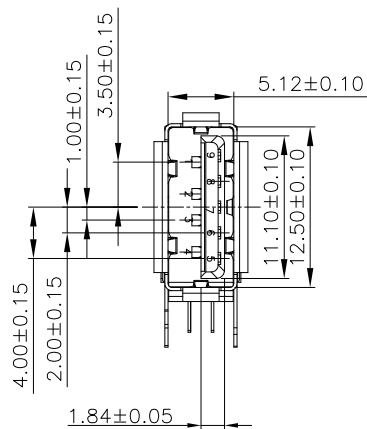
MATRIX PART NO:

MUSB 09 - 01 - 48

MATRIX USB

Pin Number

Series number

Plating
01:Gold Flash
15:15u"
30:30u"

PIN NO.	PIN 1	PIN 2	PIN 3	PIN 4	
SLGNAL NAME	V BUS	D-	D+	GND	
REMARK	USB 2.0 CONTACT PINS				
PIN NO.	PIN 5	PIN 6	PIN 7	PIN 8	PIN 9
SLGNAL NAME	STDA_SSXX-	STDA_SSXX+	GND_DRAIN	STDA_SSTX-	STDA_SSTX+
REMARK	USB 3.0 CONTACT PINS				

NO	VARIETY	QTY	METERIAL	REMARK
 Matrix Electronics Co.,Ltd 深圳市越洋達科技有限公司				
TOLERANCE: X:X X:XX ±0.20 X:XXX ±0.15 X:XXX ±0.05 ANGLE: ±3°		DESIGN BY : Phebe Su	DATE : 2015/09/07	PART NAME: 側插 USB 3.0 DIP CONN
APPROVED BY1: Richard Hsieh		DATE : 2015/09/07	PART NO.	MUSB09-01-48
APPROVED BY2: Richard Hsieh		DATE : 2015/09/07	MOLD NO.	NA
UNIT: mm [inch]		SCALE:1:1	SIZE:A4	DRAW NO.
SCALE:1:1		SIZE:A4	SHEET NO.	1 OF 1